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PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Hidenori MIKAMI	01/27/2012
Naoki MATSUMOTO	01/27/2012
Hideki OSADA	01/27/2012
Yusuke YOSHIZUMI	01/31/2012
Sayuri YAMAGUCHI	01/27/2012

RECEIVING PARTY DATA

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Postal Code:	541-0041	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13307396

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ATTORNEY DOCKET NUMBER:	201917-0120 (478621)
NAME OF SUBMITTER:	Peter J. Sistare

Total Attachments: 2

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REEL: 027705 FRAME: 0717

IOP \$40.00 13307396

ATTORNEY DOCKET NO.: 201917-0120 SOLE/JOINT INVENTION

(U.S. Rights Only)

ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

Nitride Semiconductor Substrate

for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on November 30, 2011, (Serial No. 13/307,396); and

WHEREAS, <u>Sumitomo Electric Industries</u>, <u>Ltd.</u>, a corporation of <u>Japan</u>, whose post office address is <u>5-33</u>, <u>Kitahama 4-chome</u>, <u>Chuo-ku</u>, <u>Osaka-shi</u>, <u>Osaka 541-0041</u>, <u>Japan</u>, (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to issue upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parenthesis (Application No. 13/307,396, filed November 30, 2011) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s).

THE TEST MODITE WILLEADS, IF WE Have hereuned set out manu(s).			
Full Name of Sole or First Assignor Hidenori MIKAMI	Assignor's Signature Hidenori MIKAMI	Date January 27, 2012	
Address c/o Itami Works of Sumitomo Electric Industries, Ltd., 1-1, Koyakita 1-chome, Itami-shi, Hyogo 664-0016 Japan		Citizenship Japanese	
Full Name of Second Assignor Naoki MATSUMOTO	Assignor's Signature Nachi Matsumoto	Date January 27, 2012	
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Names of additional inventors attached ⊠Yes □No			

PATENT REEL: 027705 FRAME: 0718

ATTORNEY DOCKET NO.:201917-0120

Full Name of Third Assignor Hideki OSADA	Assignor's Signature	Date January 29.2012
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Full Name of Fourth Assignor Yusuke YOSHIZUMI Address c/o Itami Works of Sumitomo Ele	Assignor's Signature Ynsuke Yoshizumi	Date Jahnaty 31, 2012 Citizenship
Address c/o Itami Works of Sumitomo Ele chome, Itami-shi, Hyogo 664-0016 Japan	Citizenship/ Japanese	
Full Name of Fifth Assignor Sayuri YAMAGUCHI	Assignor's Signature Sayum YA YIA GU CHI ectric Industries, Ltd., 1-1, Koyakita 1-	Date Some wry 27, 2012 Citizenship
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Address		Citizenship
Full Name of Ninth Assignor	Assignor's Signature	Date
Address		Citizenship
Full Name of Tenth Assignor	Assignor's Signature	Date
Address		Citizenship
Full Name of Eleventh Assignor	Assignor's Signature	Date
Address	1	Citizenship
Names of additional inventors attached \(\subseteq \)	res ⊠No	

PATENT REEL: 027705 FRAME: 0719

RECORDED: 02/15/2012